



# Product Change Notification

## 106277 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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# Product Change Notification

**Change Notification #:** 106277 - 01  
**Change Title:** Intel®TXN13600 Tunable Laser Transponder, PCN 106277-01, Product Design, Manufacturing and Assembly Site Transfer, Mechanical Modifications and Order Code, Reason for Revision: Added Class 1 laser safety option, Added firmware features to improve performance and Boot changes to improve fiber handling  
**Date of Publication:** July 10, 2006

## Key Characteristics of the Change:

Product Design  
Order Code  
Manufacturing Site

## Forecasted Key Milestones:

<b>Date of Samples Availability:</b>	Aug 04, 2006
<b>Date of Qualification Data Availability:</b>	Jul 14, 2006
<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Oct 10, 2006
<b>Date of First Availability of Post-Conversion Material:</b>	Sep 09, 2006

*The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.*

## Description of Change to the Customer:

**Reason for Revision: Added Class 1 laser safety option, added firmware features to improve performance and boot changes to improve fiber handling ( additions in red).**

Intel Corporation has qualified an additional manufacturing site for the TXN13600 full band tunable laser based transponder. This new Contract Manufacturer (CM) is located in Malaysia. Assembly and test processes in the (CM) are equivalent to those currently used in the Newark, California manufacturing facility.

All product codes covered by the PCN continue to be RoHS Level 1 compliant.

The transponder built at the CM will have the following changes:

**Hardware**

1. Second manufacturing site for tunable laser at a CM in Thailand
2. Second source for Printed Circuit Board (PCB)
3. Second source for PCB (assembly) at a CM in Malaysia
4. Second source of Mach-Zender modulator
5. Board level stuffing option to support enhanced RxLockErr operation. This option is enabled only based on specific customer request.

**Mechanical:**

1. Second source on housing and EMI shields.
2. A splice protector added between modulator and laser for additional protection.
3. A splice protector has been added between receiver and Variable optical attenuator for additional protection.
4. Redesign of fiber spool tray to hold splice protector
5. Label change with new Intel logo on TXN module, package and test report. Location of logo will remain unchanged.
6. The fiber boot on the transmit side has been modified for more robust fiber handling (increased boot length by 18 mm).

**Firmware Upgrade to enable the following features:**

1. If a transponder is switched from hard mode to soft mode, any threshold voltage applied to RxDTV pin is converted into appropriate percentage setting in the corresponding I2C registers.
2. Individual power supply alarm register reports alarm in absence of the corresponding power supply only.
3. Firmware handles incoming command overflow without interface lockup.
4. Laser control firmware revised to prevent accidental laser emission prior to laser temperature becoming stable.
5. Firmware upgrade to avoid RTOS queue overflow which may lead to I2C hang-up on rare occasions
6. Firmware enables Class 1 compliance per IEC 825-01 available on specified models.

**Customer Impact of Change and Recommended Action:**

Intel has already started builds at the CM with similar part numbers. The qualification testing report is available on July 14, 2006.

Intel will make sample parts available for customer evaluation by August 4, 2006.

Customers might receive product built at either manufacturing facility (Intel Newark or CM Malaysia) through the transition timeframe. Customers may want to inform their receiving department that either part number is acceptable. Intel is expecting to transition all the tunable transponder manufacturing to the CM by the end of 2006.

**Products Affected / Intel Ordering Codes:**

**System Products Table**

Affected Product Code	Pre-Change MM#	Post-Change Product code	Post-Change MM#	Comment
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Affected Product Code	Pre-Change MM#	Post-Change Product code	Post-Change MM#	Comment
TXN13607AF00D01	875444	TXN13607AF00DS1	883685	
TXN13607A600D01	870486	TXN13607A600DS1	883687	
TXN13607A6AAD01	879001	TXN13607A6AADS1	884275	
TXN13607AF00D01	875444	TXN13617AF00DS1	885372	Laser safety: class 1
TXN13607A600D01	870486	TXN13617A600DS1	885371	Laser safety: class1
TXN13607A6AAD01	879001	TXN13617A6AADS1	885373	Laser safety, class 1

### Reference Documents / Attachments:

**Document:**

Quality and Reliability Report (1000hr testing)

**Location #:**

Please contact your local Intel Field Sales Representative

### PCN Revision History:

**Date of Revision:**

May 9, 2006

July 10, 2006

**Revision Number:**

00

01

**Reason:**

Originally Published PCN

Added Class 1 laser safety option,  
Added firmware features to improve performance and Boot changes to improve fiber handling